

1.5mm-travel Vertical Type





Vertical push switch with two types of knob available.

Detector

Slide

Push

Rotary

Encoders

Power

Dual-in-line Package Type

TACT Switch[™]

Horizontal Type Vertical Type

Typical Specifications

Ite	ms	Specifications				
Rating (max.) / ((Resistive load)	min.)	0.1A 30V DC / 50μA 3V DC				
Contact resistan (Initial / After op		20mΩ max. / 40mΩ max.				
Operating force		Refer to the products line				
On avating life	Without load	10,000cycles				
Operating life	With load	10,000cycles (0.1A 30V DC)				

Product Line

Changeover	Travel			Terminal	Terminal Minimum order unit (pcs.)			Drawing							
timing	(mm)	(mm)	method	roles	style	force	Operation	type	Japan	Export	Product No.	No.			
					Standard	_	Latching				SPPH110800	1			
							Momentary	Straight Straight 100			SPPH110300	'			
			PC board		Short		Latching				SPPH120400	2			
						2 + 1 N	Momentary				SPPH120100				
		h 2h			Standard		Latching				SPPH130400	1			
Non shorting	1.5			2			Momentary		100	4,000	SPPH130100	'			
					Short		Latching				SPPH140300	2			
						SHOIL	SHOIL	Siloit	Short	SHOIL	SHOIL	Momentary			
					Standard	Cton doub	3 ^{+ 1} _{-0.7} N			Straight			SPPH110900	1	
						3 + 1 3 -0.7 N		Latching	Snap-in			SPPH130500			
					Short			Эпар-пі			SPPH140400	2			

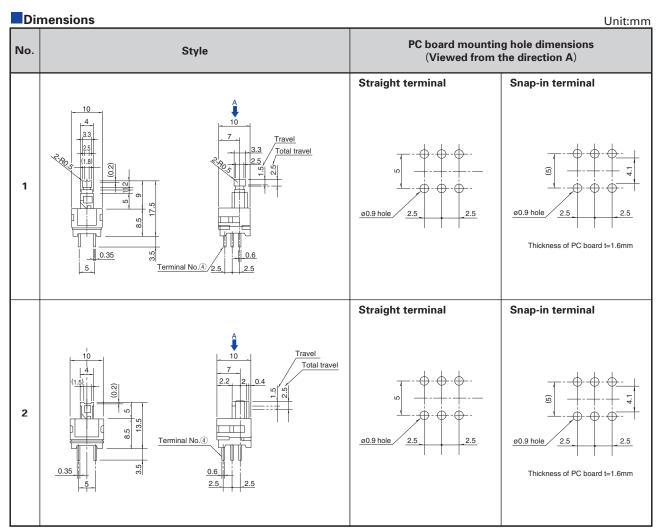
Note

Other varieties are also available. Please inquire.

Packing Specifications

Bulk

Number of p	Export package		
1 case / Japan	measurements (mm)		
800	4,000	400 × 270 × 290	



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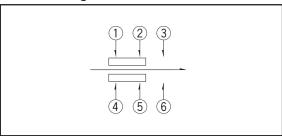
Encoders

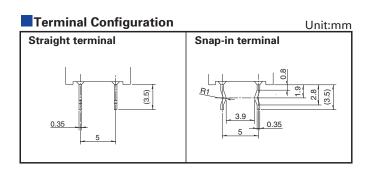
Power

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Circuit Diagram (Viewed from Direction A)





Horizontal Type

Vertical Type

Push Switches

■ List of Varieties

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TACT Switch $^{\text{TM}}$

Horizontal Type

Vertical Type	

0. :			Vertical								
	Series			SPPH4	SPPH1	SP	EF	SPED2	SPED3	SPED4	SPED5
Photo				1	8			8	Sin .		
w		6	6.5	10	9.4		14		13.5		
Dimensi (mm)		D	6.5	8.5	10	9	9	16.8	1	8	18.2
		н	6.5	8	.5	6.9		18.3	16.97	13.1	18
Tra	vel (mm))	1	2.2	1.5	1.	.5	_	_	_	_
Total t	ravel (m	ım)	1.5	3	2.5	2.	.7	4.5		3.8	
Numb	er of po	les		2		-	1	2		1	
	erating ature ra		-	10°C to +60	°C	_	40°C to +85	°C	_	40°C to +95	°C
Auton	notive ι	ıse	_	_	•	•	•	•	•	•	•
Lif	e cycle		* 3	*3	3	*	13	* * * *			*3
	ng (max stive loa		0.1A 12V DC	0.1A 3	0V DC		1A 14.5V DC 2A 14.5V DC				
	ng (min. stive loa		_	_		50 μ A 3V DC		_	_	_	_
Durability	Operat withou		10,000 cycles 50 max.	$10,000$ cycles 100 m Ω max.	10,000 cycles 40 max.	_	_	_	_	_	_
Durability	Operating li (at max. ra		$10,000$ cycles 50 m Ω max.	$10,000$ cycles 100 m Ω max.	10,000 cycles 40 max.	30,000cycles 100 m $Ω$ max.					
		contact tance	$30 \text{m}\Omega$ max.	100m Ω max.	$20 m \Omega$ max.	100mΩ max.					
Electrical performance		ation tance	100MΩ min. 500V DC			3M Ω min. 100V DC 3MΩ min. 500V DC					
		age oof	500V AC for 1minute			100V AC for 1minute					
	Tern stre	ninal ngth	5	5N for 1minute		_	_	_	_	_	Wire strength 30N
Mechanical performance	Actuator		30	N	50N	90	N	90N	98N	90N	98N
	strength	Pulling direction	_	10N	_	30N		_	_	_	_
	Co	old	-20±2°C for 96h			-40±2°C for 96h					
Environmental performance	Dry	heat	85±2°C for 96h 105±2°C for 192h								
	Damp	heat				40±2℃,	90 to 95%R	H for 96h			
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Push Switches Soldering ConditionsPush Switches Cautions137138

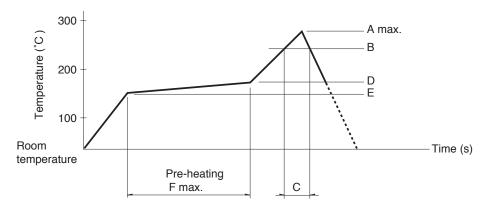
Note • indicates applicability to all products in the series.

Push Switches Soldering Conditions

■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (℃)	E (℃)	F (s)
SPEG	260	230	40	180	150	120
SPEJ						
SPEF						
SPEH						

Horizontal Type Vertical Type

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time		
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±5℃	3+1/0s		
SPED2, SPED4	350±5℃	3±1s		
SPEJ	350±5℃	4s max.		
SPEG, SPPH2, SPEF	350±10°C	3s max.		
SPEH	350°C max.	3s max.		
SPUJ, SPUP	300±5℃	3+1/0s		

Reference for Dip Soldering

(For PC board terminal types)

Series	Ite	ms	Dip soldering		
Series	Preheating temperature Preheating time		Soldering temperature	Duration of immersion	
SPPJ3	100°C max.	100°C max. 60s max.		5±1s	
SPUN	100°C max. 60s max.		260±5℃	10±1s	
SPUJ, SPUP, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

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